

ABSTRACT

[0053] A method for fabricating features on a substrate having reduced dimensions is provided. The features are formed by defining a first mask through one or more layers of a multilayer stack formed on a substrate. The first mask is defined using lithographic techniques. A second mask is then conformably formed on one or more sidewalls of the first mask. Using the second mask as an etch mask, the remaining layers of the multilayer stack are etched to the substrate surface forming an opening in the multilayer stack. The features are completed by filling the opening with one or more material layers followed by removal of the multilayer stack.